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## **PRODUCT BULLETIN # 20247**

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**Issue Date:** 16-Oct-2013

**TITLE:** Change Unit Probe to Sample Probe

**PROPOSED FIRST SHIP DATE:** 16-Oct-2013

**AFFECTED CHANGE CATEGORY(S):** Standard Product Group (SPG)

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor sales office or <MohdHezri.AbuBakar@onsemi.com>

**NOTIFICATION TYPE:**

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

**DESCRIPTION AND PURPOSE:**

On Semiconductor is doing a change on wafer probe measurement from unit probe to sample probe for some TMOS7 devices to maximize the probe capacity.

Final test at post-assembly device level has extensive coverage compared to probe test. Sample probe is good enough to check the dice on wafer level are functional and meeting critical electrical parameters. Changing from unit probe to sample probe does not degrade the test quality and defects detection capability that we have for end products.



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**List of affected Standard Parts:**

NTB25P06T4G  
NTB45N06T4G  
NTB5605PT4G  
NTBV45N06T4G  
NTBV5605T4G  
NTC3055L104WP  
NTD18N06LT4G  
NTD20N06T4G  
NTD20P06LG  
NTD20P06LT4G  
NTD2955-1G  
NTD2955G  
NTD2955T4G  
NTD3055L104-1G  
NTD3055L104G  
NTD3055L104T4G  
NTDV20P06LT4G  
NTDV3055L104T4G  
NTF2955T1G  
NTF3055L108T1G  
NTP2955G  
NVB25P06T4G  
NVD2955T4G  
NVF2955T1G  
NVF3055L108T1G  
NVF3055L108T3G